



NOTE

- 1 IT3-300P-***H(**) to be mounted and locked to IT3M receptacle.
- 2 Lot no. is marked on top of the connector.
- 3 Minimum clearance for all devices.
- 4 Minimum clearance for sensitive devices.
- 5 More information of this product is available in HIROSE document : ETAD-F0347 "IT3 Design Guideline".
- 6 Maximum coplanarity of the ball field is 0.18 mm.
- 7 Please remove the pick up cap (part No.6) from the IT3 connector after reflow soldering.
- 8 The removed pick up cap (part No.6) should not be reused.
- 9 Standard package of 48pcs are packaged in a carton box.
- 10 This product is categorized in the MSL2A of IPC/JEDEC J-STD-020B. It is recommended to use within four weeks, defined by JEDEC, in the office environment after unpacked.
- 11 This product is a solder ball locations and co planarity sensitive BGA connector. It is recommended to handle this product with the automated machine. Solder ball locations and co planarity might be damaged accidentally when it is manually handled by assembly workers.

3	Copper alloy	Contact area : Nickel(1.5µm) + Gold(0.76µm) Other area : Nickel(1.5µm)	6	SUS	PICK UP CAP							
2	LCP	BLACK . UL94V-0	5	HIPS	TRAY . BLACK							
1	LCP	BLACK . UL94V-0	4	TIN-LEAD	Sn(63)-Pb(37)							
NO.	MATERIAL	FINISH, REMARKS	NO.	MATERIAL	FINISH, REMARKS							
UNITS	mm	SCALE	2:1	REV/COUNT	1	DESCRIPTION OF REVISIONS	DESIGNED	TS. KIKUCHI	CHECKED	TS. MATSUO	DATE	09.10.16
APPROVED		T. Matsuo	07/26/2007	DRAWING NO.		EDC3-157109-02						
CHECKED		T. Matsuo	07/26/2007	PART NO.		IT3M-300S-BGA(57)						
DESIGNED		T. Takada	07/26/2007	CODE NO.		CL636-0008-1-57						
DRAWN		T. Takada	07/26/2007									

